

## Claims

1. A method including:

a) providing a wafer having a plurality of microfabricated devices  
5 formed thereon;

b) applying a plurality of substantially hollow caps to a first side of the  
wafer, the caps positioned such that, in plan view, each cap overlays part or all of at  
least one microfabricated device and whereby the periphery of each cap is remote  
from the periphery of any adjacent cap;

10 c) applying one or more etches to the wafer from the first side toward  
the other side to etch away at least some of the material between the peripheries of  
said caps to separate the wafer into separate units.

2. The method of claim 1 wherein the first side is the bottom side of the wafer.

15 3. The method of claim 1 wherein caps are applied to both sides of the wafer

4. The method of claim 1 wherein a first plurality of caps are applied to the bottom  
side of the wafer and a second plurality of caps are applied to the top side of the wafer.

20 5. The method of claim 1 wherein a first plurality of caps are applied to the bottom  
side of the wafer and a second plurality of caps are applied to the top side of the wafer and,  
wherein, in plan view, each of the second plurality of caps overlays all or  
part of one or more microfabricated devices; and,  
25 in plan view, each of the first plurality of caps cover the corresponding  
second cap.

6. The method of claim 1 wherein the caps are joined together by a thin layer of  
material extending between the periphery of each of the caps.

30 7. The method of claim 1 wherein the caps are joined together by a thin layer of  
material extending between the periphery of each of the caps and the thin layer is removed  
by an oxygen plasma etch after step b) and prior to step c).